# Report on Insulated Gate Bipolar Transistors (IGBTs)

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### 1 Introduction

#### 1.1 Definition of IGBT

An Insulated Gate Bipolar Transistor (IGBT) is a three-terminal power semiconductor device primarily used in high-power applications. It combines the high input impedance and fast switching capabilities of a Metal-Oxide-Semiconductor Field-Effect Transistor (MOSFET) with the high current and low saturation voltage characteristics of a Bipolar Junction Transistor (BJT). IGBTs are widely used in power electronics applications such as inverters, motor drives, and power supplies.

# 2 Key Parameters of IGBTs

#### 2.1 Breakdown Voltage (V<sub>CEmax</sub>)

**Definition**: The maximum voltage that can be applied between the collector and emitter without causing breakdown.

**Importance**: Determines the maximum voltage the IGBT can handle in operation. Must be selected based on the peak voltages in the application.

## 2.2 Collector Current (I<sub>C</sub>))

**Definition**: The maximum continuous current that can flow through the collectoremitter channel without causing damage to the device.

**Importance**: A critical parameter for ensuring the IGBT can handle the load current in applications such as motor drives.

## 2.3 Gate Threshold Voltage $(V_{GE(th)})$

**Definition**: The gate-emitter voltage at which the IGBT begins to turn on. **Importance**: Influences the drive circuit design and ensures proper switching behavior.

# 2.4 On-State Voltage Drop (V<sub>CE(on)</sub>))

**Definition**: The voltage drop across the collector-emitter terminals when the IGBT is in the on state.

Importance: A lower  $V_{CE(on)}$  reduces conduction losses, improving efficiency.

# 2.5 Switching Times $(t_{on})$ , $t_{off}$ )

#### **Definition**:

- $\mathbf{t_{on}}$ : Time required for the IGBT to turn on.
- $\mathbf{t}_{\text{off}}$ : Time required for the IGBT to turn off.

**Importance**: Faster switching times reduce switching losses, which is crucial in high-frequency applications.

## 2.6 Gate Charge (Q<sub>g</sub>)))

**Definition**: The total charge required to turn the IGBT on or off.

**Importance**: Affects the power required from the gate drive circuit and influences the switching speed.

## 2.7 Power Dissipation (P<sub>D</sub>)))

**Definition**: The maximum power the IGBT can dissipate as heat under specified conditions.

**Importance**: Determines the thermal design requirements and affects reliability.

## 2.8 Thermal Resistance $(R_{\theta JA}, R_{\theta JC})$

#### **Definition:**

- $\mathbf{R}_{\theta \mathbf{J} \mathbf{A}}$ : Junction-to-ambient thermal resistance.
- $\mathbf{R}_{\theta \mathbf{JC}}$ : Junction-to-case thermal resistance.

**Importance**: Lower thermal resistance allows for better heat dissipation, enhancing device longevity.

## 2.9 Short Circuit Withstand Time $(t_{SC})$ )

**Definition**: The duration for which the IGBT can withstand a short circuit condition without being damaged.

**Importance**: Critical for ensuring robustness in applications where short circuit conditions might occur.

## 2.10 Input Capacitance (Cies)))

**Definition**: The capacitance seen at the gate terminal when the device is in operation.

**Importance**: Influences the switching characteristics and the design of the gate drive circuit.

# 3 Operating Regions of IGBTs

#### 3.1 Cut-off Region

**Operation**: When the gate-emitter voltage  $(V_{GE})$  is below the threshold voltage, the IGBT is in the off state, and no current flows between the collector and

emitter.

**Application**: Used when the IGBT is intended to block current flow.

#### 3.2 Active Region

**Operation**: When  $V_{\rm GE}$  exceeds the threshold voltage, the IGBT enters the active region, where it behaves like a current-controlled current source.

**Application**: This region is typically avoided in most applications to minimize power dissipation.

#### 3.3 Saturation Region

**Operation**: When the IGBT is fully turned on  $(V_{GE}$  is significantly higher than  $V_{GE(th)})$ , it operates in the saturation region, allowing maximum current flow with minimal voltage drop.

**Application**: Ideal for switching applications where the IGBT needs to conduct large currents efficiently.

# 4 Summary

IGBTs are vital components in high-power electronic systems, offering a combination of the benefits of MOSFETs and BJTs. Understanding key parameters like breakdown voltage, collector current, on-state voltage drop, and switching times is essential for selecting the right IGBT for specific applications. The operating regions—cut-off, active, and saturation—define how the IGBT functions under different conditions, which is critical for designing efficient and reliable circuits.